

**Ordering number C12500\_MIRA-M**

Family	Mira	FWHM	30 degrees
Type	Lens	Efficiency	82 %
LED	BXRA ES Star	cd/lm	(simulated) 0.000
Color	Clear	Gerber File	Available
Diameter	32.4 mm		
Height	14.7 mm		
Style	Round		
Optic Material	PC		
Holder Material	-		
Fastening	-		
Status	On production		

**Ordering number C12501\_MIRA-W**

Family	Mira	FWHM	39 degrees
Type	Lens	Efficiency	82 %
LED	BXRA ES Star	cd/lm	(simulated) 0.000
Color	Clear	Gerber File	Available
Diameter	32.4 mm		
Height	14.7 mm		
Style	Round		
Optic Material	PC		
Holder Material	-		
Fastening	-		
Status	On production		

**Ordering number C12502\_MIRA-WW**

Family	Mira	FWHM	54 degrees
Type	Lens	Efficiency	83 %
LED	BXRA ES Star	cd/lm	(simulated) 0.000
Color	Clear	Gerber File	Available
Diameter	32.4 mm		
Height	14.7 mm		
Style	Round		
Optic Material	PC		
Holder Material	-		
Fastening	Glue		
Status	On production		



**NOTE: The typical divergence will be changed by different color, chip size and chip position tolerance. The typical total divergence is the full angle measured where the luminous intensity is half of the peak value.**

**GENERAL INFORMATION**

- Product series especially designed & optimized for BXRA ES Star series of LEDs.
- Special care taken to make light distribution as uniform as possible.
- Lens material optical grade PC with high UV and temperature resistance (120 degrees of Celcius / 248 degrees of Fahrenheit). Allows use of high current and temperature conditions.

Please find more information about used materials from below:

[http://ledil.fi/sites/default/files/Documents/Technical/Material/PC%20Makrolon%202400\\_2407\\_2456\\_2458-UL.pdf](http://ledil.fi/sites/default/files/Documents/Technical/Material/PC%20Makrolon%202400_2407_2456_2458-UL.pdf)

- Fastening to PCB with appropriate adhesive. By clicking link below you can find Ledil recommended glue options.

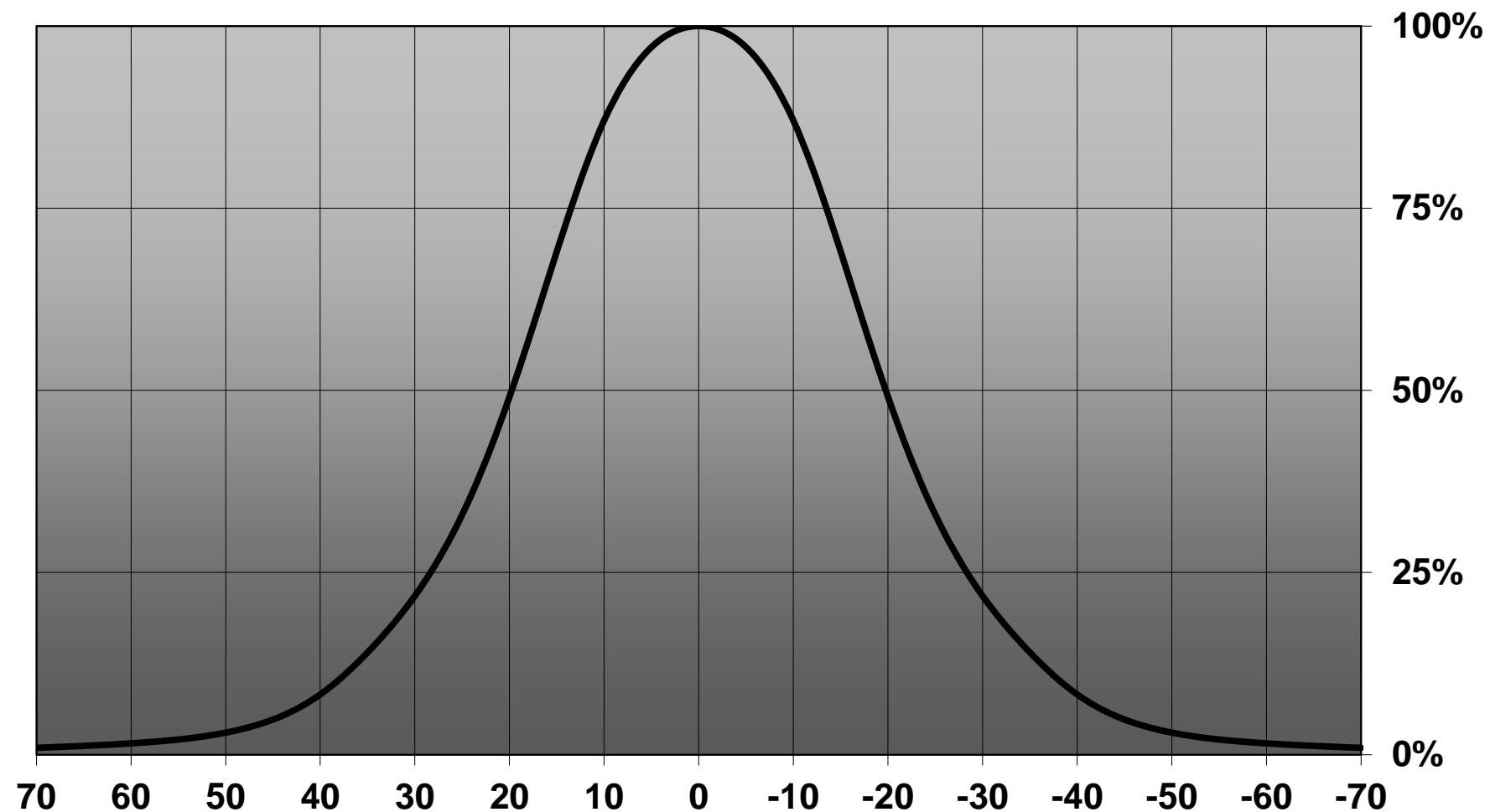
[http://www.ledil.com/datasheets/DataSheet\\_GLUES.pdf](http://www.ledil.com/datasheets/DataSheet_GLUES.pdf)

**NOTE 1: We advise customer to ensure the suitability and sufficiency of the bond in the end product. For example, mechanical stress, vibration and holes on the surface of the circuit board weaken the strength of the glue.**

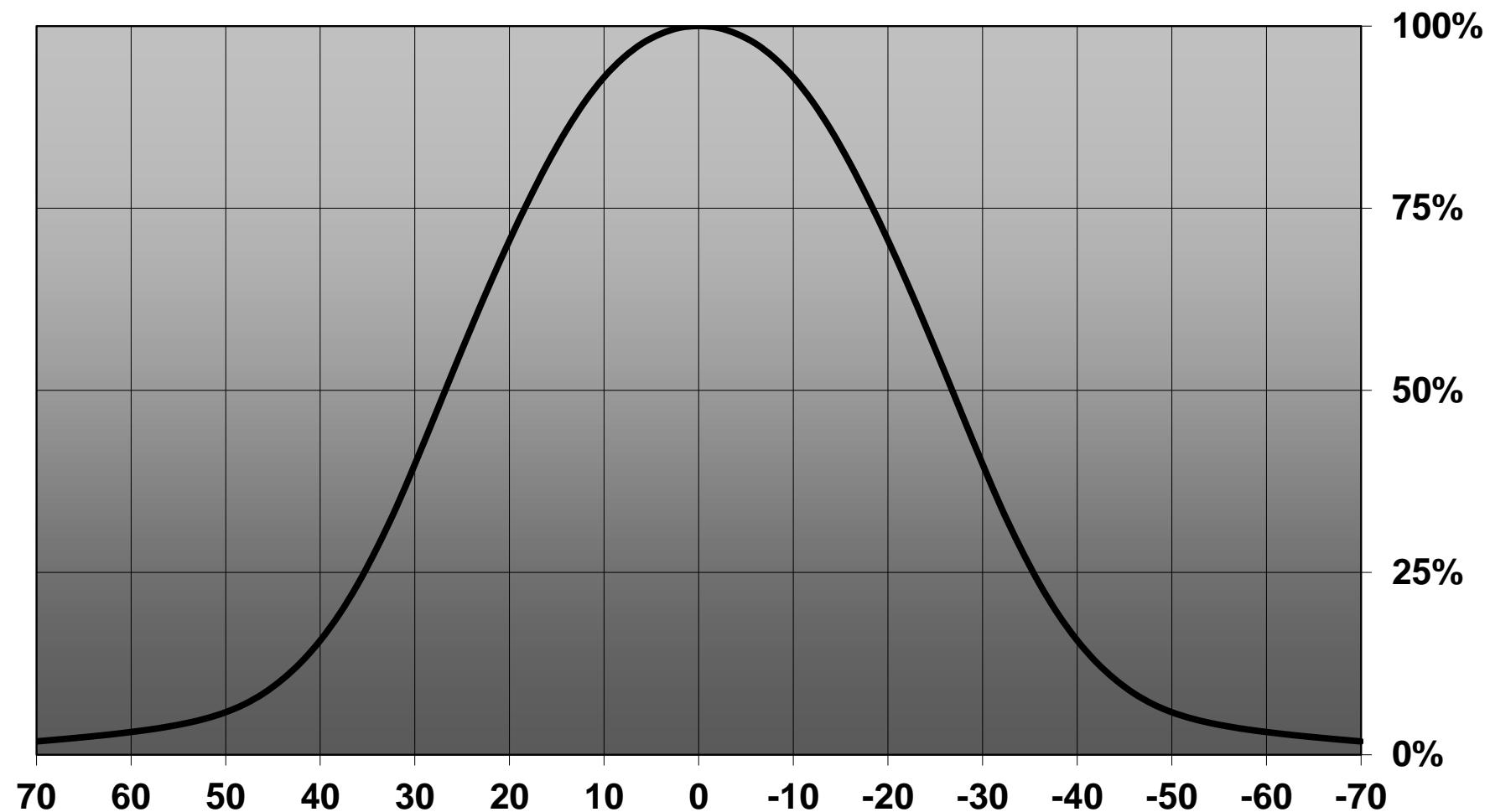
**NOTE 2: All surfaces where glue is applied must be clean, dry and free from grease and dirt. If cleaning of PCB surfaces is needed, please follow strictly the cleaning instructions of your LED manufacturer -this is important as cleaning shall under no circumstances damage LEDs or other electronics components on the PCB.**

**Further note that optical components shall not be cleaned with any chemicals - only micro fiber cloth may be used to remove fingerprints or other traces from handling.**

### Relative intensity of C12501\_MIRA-W (BXRA-W0400)



### Relative intensity of C12502\_MIRA-WW (BXRA-W0400)

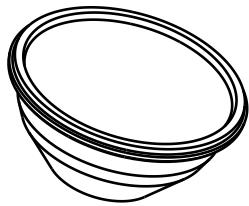


D

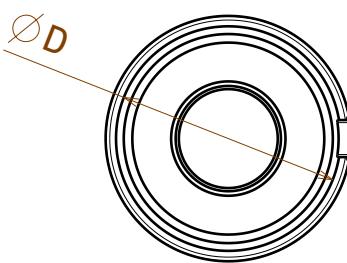
C

B

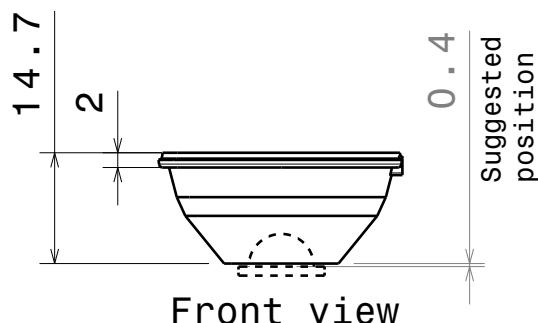
A



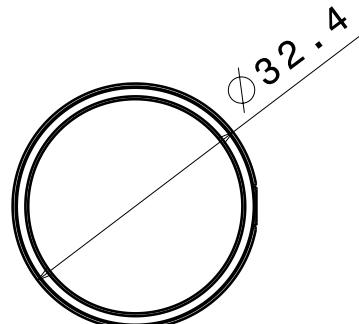
Isometric view



Bottom view



Front view



Top view

## Dimension D:

- C12500\_MIRA-M 29,7mm
- C12501\_MIRA-W 28,4mm
- C12502\_MIRA-WW 28,4mm

Material: PC

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Ledil Oy  
Salorankatu 10  
FIN 24240 SALO  
Finland

## DRAWING TITLE

## Datasheet MIRA lens

DRAWN BY mav	DATE 02.04.2012	SIZE A4	DRAWING NUMBER -	REV 1
CHECKED BY sn	DATE 02.04.2012			
DESIGNED BY mav	DATE 29.11.2011	SCALE 1:1	WEIGHT(g)	SHEET 1/1

D

A